

# Analysis and Measurement of Resonant Tank Current on LLC

Max Han, Zhong Ye

Power Management/Field Application

## ABSTRACT

Wide input voltage range and high efficiency of front-end converters are required in many applications. Most PWM DC-DC converters cannot meet these requirements because of low efficiency at the wide input voltage range. As a result, LLC is put forward to achieve both high efficiency and wide input voltage range capability because of its voltage gain characteristics and small switching loss<sup>[1]</sup>. This application report presents analysis of resonant tank current on LLC. Three current measurements of power resistance, current transformer, and current probe are discussed and compared, and the advantages, disadvantages, and applications of these current measurements are presented. The experiment result matches theoretical analysis.

#### Contents

1. Introduction	2
2. Analysis of Resonant Tank Current	2
3. Resonant Tank Current Measurement Method	6
4. Experiment	9
5. Conclusion	10
References:	10

## Figures

Figure 1.	LLC Resonant Half-bridge Converter	2
Figure 2.	Waveform at f <sub>m</sub> <f<sub>s<f<sub>r</f<sub></f<sub>	3
Figure 3.	Simplified Circuit at t₂ <t<t₃< td=""><td>4</td></t<t₃<>	4
Figure 4.	Equivalent Model of Current Transformer	6
Figure 5.	Resonant Tank Current Measured by Different Methods	8
Figure 6.	Resonant Tank Current, DS Voltage and V <sub>cr</sub> Waveform During ZVS	9
U		

#### Tables

9	)
•	9



# 1. Introduction

LLC is the best candidate of front-end DC-DC converter for wide input voltage range and high efficiency. UCC25600 is designed for DC/DC applications utilizing resonant topologies, especially the LLC half bridge resonant converter. This highly integrated controller has only 8 pins and small package, which will greatly simplify the system design, layout and accelerate product time to market <sup>[2]</sup>. So LLC half bridge resonant converter is as example to analyze resonant tank current.

# 2. Analysis of Resonant Tank Current

Figure 1 is an LLC resonant half-bridge converter circuit.

- S<sub>1</sub> and S<sub>2</sub> are primary MOSFETs.
- C<sub>S1</sub> and C<sub>S2</sub> are parasitic capacitors between drain and source of MOSFET.
- D<sub>s1</sub> and D<sub>s2</sub> are body diodes of MOSFET.
- L<sub>r</sub> and C<sub>r</sub> are resonant inductor and resonant capacitor.
- L<sub>m</sub> is the magnetic inductor of transformer.
- n is the turns ratio of primary and secondary turns.
- The secondary rectifier contains D<sub>1</sub> and D<sub>2</sub>.
- C<sub>o</sub> is the output capacitor.
- R<sub>L</sub> is the load.
- V<sub>in</sub> is input voltage and V<sub>o</sub> is output voltage.



Figure 1. LLC Resonant Half-bridge Converter



There are two resonant frequencies on the LLC resonant converter: one is produced by  $L_r$  and  $C_r$ , which is shown as equation 1; the other is produced by  $L_r$ ,  $L_m$ , and  $C_r$ , which is shown as equation 2. Generally, LLC is designed to operate at  $f_r$  for nominal input voltage, thus the best efficiency will be achieved. Switch frequency is larger than  $f_r$ . ZVS of primary MOSFET can be realized, but ZCS of secondary diode cannot be achieved; it is called LC series resonance. When switch frequency is lower than  $f_r$  but higher than  $f_m$ , both ZVS and ZCS can be realized. Because the resonance of  $L_r$ ,  $L_m$ , and  $C_r$  occurs in a period, it is called LLC series resonance. In reference [3], switch frequency at most of the load range is lower than  $f_r$ , so the operation where frequency is lower than  $f_r$  is analyzed in this application report.

$$f_r = \frac{1}{2\pi\sqrt{L_r C_r}} \tag{1}$$

$$f_m = \frac{1}{2\pi\sqrt{(L_r + L_m)C_r}} \tag{2}$$

Figure 2 is the waveform at  $f_m < f_s < f_r$ , half period is divided into four parts. A voltage spike of  $t_2$  to  $t_3$  is concerned, so this period is described in the following paragraphs. All equations show the relations of power parameters.



Figure 2. Waveform at f<sub>m</sub><f<sub>s</sub><f<sub>r</sub>

At t<sub>2</sub>, high-side MOSFET S<sub>1</sub> is turned off, but low-side MOSFET is still off, so t<sub>2</sub> is the beginning of dead time. During this period, resonant tank current cannot flow through MOSFET; it charges C<sub>s1</sub> and discharges C<sub>s2</sub>. C<sub>s1</sub> and C<sub>s2</sub> participate resonance. C<sub>s1</sub> and C<sub>s2</sub> are equal and small, so this period is very short. ZVS is achieved quickly. In real systems  $C_r >> C_{s1}$ , so in this period, V<sub>Cr</sub> nearly does not change; it could be regarded as a DC voltage source. Figure 3 shows a simplified circuit.



Figure 3. Simplified Circuit at t<sub>2</sub><t<t<sub>3</sub>

All parameters are shown as equations 3 and 4, and the resonant frequency is equal to equation 5. Because of  $C_{eq}$ ,  $fr_3$  is extremely larger than  $fr_1$  and  $fr_2$ .

$$v_{Ceq} + (L_r + L_m)C_{eq} \frac{d^2 v_{Ceq}}{dt^2} = V_{Cr}$$
(3)

$$i_{Lr} = i_{Lm} = C_{eq} \frac{\mathrm{d}v_{Ceq}}{\mathrm{d}t} \tag{4}$$

$$f_{r3} = \frac{1}{2\pi\sqrt{(L_r + L_m)C_{eq}}}$$
(5)

Where,  $C_{eq} = C_{s1} + C_{s2} = 2C_{s1}$ 

The value of the change in the resonant tank current in this period is researched, so an equation to describe resonant tank current at the time domain is required. The actual beginning time of this period is  $t_2$  and the ending time is  $t_3$ . To simplify calculation, assume the beginning time of this period is 0 and the ending time of this period is  $t_a$ . At 0, the voltage of  $v_{Ceq}$  is  $\frac{1}{2}V_{in}$ , the resonant tank current is  $I_{Lr}$ , so  $v_{Ceq}(0) = \frac{1}{2}V_{in}$ ,  $i_{Lr}(0) = I_{Lr}$ . At  $t_a$ , the voltage of  $v_{Ceq}$  is  $-\frac{1}{2}V_{in}$ , so  $v_{Ceq}(t_a) = -\frac{1}{2}V_{in}$ .

According to equation 3,  $v_{Cea}(t)$  could be obtained as follows:

$$v_{Ceq}(t) = p_1 \cos(\frac{1}{\sqrt{(L_r + L_m)C_{eq}}}t) + p_2 \sin(\frac{1}{\sqrt{(L_r + L_m)C_{eq}}}t) + V_{Cr}$$
(6)



Where,  $p_1$  and  $p_2$  are constants. We define  $\omega_{rm} = \frac{1}{\sqrt{(L_r + L_m)C_{eq}}}$ , so equation 6 is simplified.

$$v_{Ceq}(t) = p_1 \cos(\omega_{rm} t) + p_2 \sin(\omega_{rm} t) + V_{Cr}$$
(7)

 $i_{Ir}(t)$  is expressed as equation 8.

$$i_{Lr}(t) = -i_{Ceq}(t) = -C_{eq} \frac{dv_{Ceq}(t)}{dt} = C_{eq} p_1 \omega_{rm} \sin(\omega_{rm} t) - C_{eq} p_2 \omega_{rm} \cos(\omega_{rm} t)$$
(8)

 $v_{Ceq}(0) = \frac{1}{2}V_{in}$  and  $i_{Lr}(0) = I_{Lr}$  are put into equations 7 and 8 separately, the constant coefficients  $p_1$  and  $p_2$  are derived as follows:

$$p_1 = \frac{1}{2} V_{in} - V_{Cr}$$
(9)

$$p_2 = -\frac{I_{Lr}}{C_{eq}\omega_{rm}} \tag{10}$$

$$v_{Ceq}(t_a) = -\frac{1}{2}V_{in}$$
 is put into equation 6.

$$p_1 \cos(\omega_{rm} t_a) + p_2 \sin(\omega_{rm} t_a) + V_{Cr} = -\frac{1}{2} V_{in}$$
(11)

According to equation 11,  $\sin(\omega_{rm}t_a)$  and  $\cos(\omega_{rm}t_a)$  can be deduced.

 $i_{Lr}(t_a)$  is shown is equation 12. Because all parameters are derived, the exact value of  $i_{Lr}(t_a)$  can be obtained.

$$i_{Lr}(t_a) = C_{eq} p_1 \omega_{rm} \sin(\omega_{rm} t_a) - C_{eq} p_2 \omega_{rm} \cos(\omega_{rm} t_a)$$
(12)

The change of the resonant tank current in this period is called  $\Delta i_{Lr}$ , which is shown as follows:

$$\Delta i_{Lr} = i_{Lr}(t_a) - I_{Lr} \tag{13}$$

Generally,  $\Delta i_{Lr}$  is omitted in analysis of resonant tank current, because its value is smaller than the peak value of resonant tank current and the period of this transition is extremely shorter than the switch period. However, this quick transition introduces noise to the measurement circuit. The preceding equations can verify if the result of the measurement is true. When it is false, the measurement circuit should be improved.



## 3. Resonant Tank Current Measurement Method

When current waveform is required, three methods can be adopted to measure the current.

- Power resistance with small tolerance
- Current transformer (CT)
- Measure resonant tank current directly by current probe

The first method is power resistance with small tolerance, which is in series with other components in the resonant loop. The resistance must have high resolution and good temperature performance. Normally, the resonant loop is connected to ground by one terminal, which can reduce common mode noise when measured. This method is also an easy way to measure resonant tank current. However, it increases power loss especially at high current. On the other hand, it changes the resonant parameter and makes the operation deviate from the original design. This method also has a high price because of the high performance required.



Figure 4. Equivalent Model of Current Transformer

The second method is CT, where the primary side is in series in the resonant loop. Compared with power resistance (the first method), this method has low resistance and its power loss is lower than the power resistance. Moreover, compared with  $L_r$  and  $L_m$  of the resonance loop, the magnetic inductance of CT is small enough and can be ignored. However, CT is not an optimal solution because of many parasitic parameters. Figure 4 is the equivalent model of CT. Because the secondary leakage inductance is much larger than the primary leak inductance, leakage inductance is set at the secondary side.

In Figure 4:

- C<sub>ps</sub> is the parasitic capacitance between primary turns and secondary turns.
- C<sub>p</sub> is the parasitic capacitance of the primary side.
- C<sub>s</sub> is the parasitic capacitance of the secondary side.
- L<sub>m</sub> is the magnetic inductance of CT.
- R is the sample resistance.



When MOSFET turns on or turns off at hard switch, the state of the circuit changes instantly and fiercely. Much switch noise is produced at this time. This noise is coupled to the secondary side of CT through  $C_{ps}$ . Noise also flows through  $C_p$  and  $C_s$ .  $L_m$  and  $L_{leak}$  are also affected. If a generic voltage probe is used to measure the voltage of R, normally a high voltage spike occurs; however; if a differential voltage probe is adopted, the common mode noise coupled by  $C_{ps}$  is eliminated, and only differential mode noise remains. Voltage spike is reduced efficiently. However, waveform measured by differential voltage probe is still not the real current waveform.

The third method is to measure resonant tank current directly by current probe. Normally, current probe has a high bandwidth, which is enough for power system test. For example, TCP202 designed by Tektronix is a DC-coupled current probe, which has a bandwidth of DC to 50 MHz. The LLC resonant tank current frequency is 100 kHz. Current probe has a good performance, which can display a nearly real current waveform. Only a short wire is needed, and it is in series with other components in loop, so this is the least expensive method to view current waveform. However, the current signal measured by current probe cannot be used for other purpose, such as loop control, protection, and so forth.

UCC25600 300W EVM demonstrates the preceding analysis. In Figure 5, resonant tank current is measured by different methods. CH2 and CH3 are both measured by CT, the difference is that a *differential* voltage probe is used to sample voltage signal which is the voltage at the output side of CT in CH2, but a *common* voltage probe is used to sample voltage signal, which is the voltage at the output side of CT in CH3. CH4 is measured by current probe directly. In Figure 5(b) and 5(c), CH2 and CH3 are measured separately, but in Figure 5(d), they are measured at the same time. In Figure 5(a), compared with CH4, large current pulse can be seen in CH3, which is big noise. In Figure 5(b) and Figure 5(c), compared with CH3, current pulse of CH2 is reduced greatly because common mode noise is eliminated; however, differential mode noise still exists, so current pulse of CH2 is larger than that of CH4. In Figure 5(d), CH2 and CH3 are measured at the same time, because all of the grounds of the probes of the oscilloscope are connected at the internal oscilloscope. Common mode noise of CH3 will affect CH2. The waveforms of CH2 and CH3 are the same in Figure 5(d), which proves that in Figure 5(b) and Figure 5(c), CH3 equals the result that CH2 pulses common mode noise.



**STRUMENTS** 

Figure 5. Resonant Tank Current Measured by Different Methods

According to experiment result, the preceding analysis is certified. Power resistance is used at the condition of low current, and sampled current signal could be used for other functions. CT is adopted at the condition of high current, and sampled current signal could be used for other functions. If compensation and filter are added on the CT, it is better. Current probe is applied at all conditions, but its sampled current signal cannot be used for other functions.

**NOTE:** Small range current probe is recommended to measure low current. Similarly, large range current probe is recommended to measure high current.



# 4. Experiment

To validate the analysis of Section 2, LLC resonant half-bridge converter 300-W evaluation module of TI is used to obtain data of seven groups. All parameters have been designed and optimized,  $L_r = 55 \mu$ H,  $L_m = 280 \mu$ H,  $C_r = 24 n$ F,  $C_{s1} = 340 p$ F,  $V_{in}$ ,  $V_{Cr}$  and  $I_{Lr}$  must be measured.

Figure 6 shows resonant tank current, DS voltage and  $V_{Cr}$  waveform during ZVS, where, CH2 is resonant tank current waveform. In Figure 6(a), CH1 is DS voltage waveform. In Figure 6(b), CH1 is the voltage of  $C_r$  waveform. Resonant tank current is measured by current probe, DS voltage and  $C_r$  voltage are measured by differential voltage probe.

All data are listed in Table 1:  $I_{Lr1}$  is the value of  $I_{Lr}$  at the beginning of ZVS,  $I_{Lr2}$  is the value of  $I_{Lr}$  at the end of ZVS,  $\Delta I = I_{Lr1} - I_{Lr2}$ , and  $\Delta I_{cal}$  is the result calculated by from equation 13 to equation 20. Because these equations are too complex, Mathcad is adopted to make calculation easy. Comparing  $\Delta I$  and  $\Delta I_{cal}$ ,  $\Delta I_{cal}$  approaches  $\Delta I$ , which certifies that the analysis of reference [3] in Section 2 is correct and reasonable. The differential value of  $\Delta I$  and  $\Delta I_{cal}$  is caused by parasitic parameters and measurement error.





V <sub>in</sub> (V)	V <sub>Cr</sub> (V)	I <sub>Lr1</sub> (A)	ILr2(A)	ΔI(A)	ΔI <sub>cal</sub> (A)
392.7	237.4	1.517	1.32	0.197	0.130
392.6	249.9	1.541	1.358	0.183	0.135
390.5	268.0	1.550	1.357	0.193	0.144
390.5	288.3	1.584	1.375	0.209	0.152
390.6	307.7	1.623	1.440	0.183	0.158
390.6	328.1	1.659	1.460	0.199	0.165
390.6	348.2	1.677	1.476	0.201	0.174

Гable 1.	The Value of Parameters



## 5. Conclusion

LLC can provide high efficiency at a wide input voltage range. Resonant tank current of LLC is analyzed, and numerous equations specify the relations of all power parameters. Three current measurements are discussed and their applications, advantages, disadvantages are presented. The analysis is certified by experiment results.

## **References:**

[1] Ya Liu. High Efficiency Optimization of LLC Resonant Converter for Wide Load Range. Blacksburg, Virginia: Master's Degree Thesis of Virginia Polytechnic Institute and State University, 2007.

[2] 8-Pin High-Performance Resonant Mode Controller. Texas Instruments UCC25600 Data Sheet, SLUS846B, September 2008, Revised July 2011.

[3] LLC Resonant Half-Bridge Converter 300-W Evaluation Module. Texas Instruments User's Guide, SLUU361, April 2009.

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconr	nectivity	

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2013, Texas Instruments Incorporated